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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	18MHz
Connectivity	I²C, UART/USART
Peripherals	Brown-out Detect/Reset, LED, POR, PWM, WDT
Number of I/O	18
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 3.6V
Data Converters	A/D 4x8b; D/A 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	20-TSSOP
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/p89lpc924fdh-529

2.2 Additional features

- 20-pin TSSOP package.
- A high performance 80C51 CPU provides instruction cycle times of 111 ns to 222 ns for all instructions except multiply and divide when executing at 18 MHz. This is six times the performance of the standard 80C51 running at the same clock frequency. A lower clock frequency for the same performance results in power savings and reduced EMI.
- In-Application Programming of the Flash code memory. This allows changing the code in a running application.
- Serial Flash programming allows simple in-circuit production coding. Flash security bits prevent reading of sensitive application programs.
- Watchdog timer with separate on-chip oscillator, requiring no external components. The watchdog prescaler is selectable from eight values.
- Low voltage reset (Brownout detect) allows a graceful system shutdown when power fails. May optionally be configured as an interrupt.
- Idle and two different Power-down reduced power modes. Improved wake-up from Power-down mode (a low interrupt input starts execution). Typical Power-down current is 1 μA (total Power-down with voltage comparators disabled).
- Active-LOW reset. On-chip power-on reset allows operation without external reset components. A reset counter and reset glitch suppression circuitry prevent spurious and incomplete resets. A software reset function is also available.
- Oscillator Fail Detect. The watchdog timer has a separate fully on-chip oscillator allowing it to perform an oscillator fail detect function.
- Programmable port output configuration options:
  - quasi-bidirectional,
  - open drain,
  - push-pull,
  - input-only.
- Port ‘input pattern match’ detect. Port 0 may generate an interrupt when the value of the pins match or do not match a programmable pattern.
- LED drive capability (20 mA) on all port pins. A maximum limit is specified for the entire chip.
- Controlled slew rate port outputs to reduce EMI. Outputs have approximately 10 ns minimum ramp times.
- Only power and ground connections are required to operate the P89LPC924/925 when internal reset option is selected.
- Four interrupt priority levels.
- Eight keypad interrupt inputs, plus two additional external interrupt inputs.
- Second data pointer.
- Schmitt trigger port inputs.
- Emulation support.

4. Block diagram

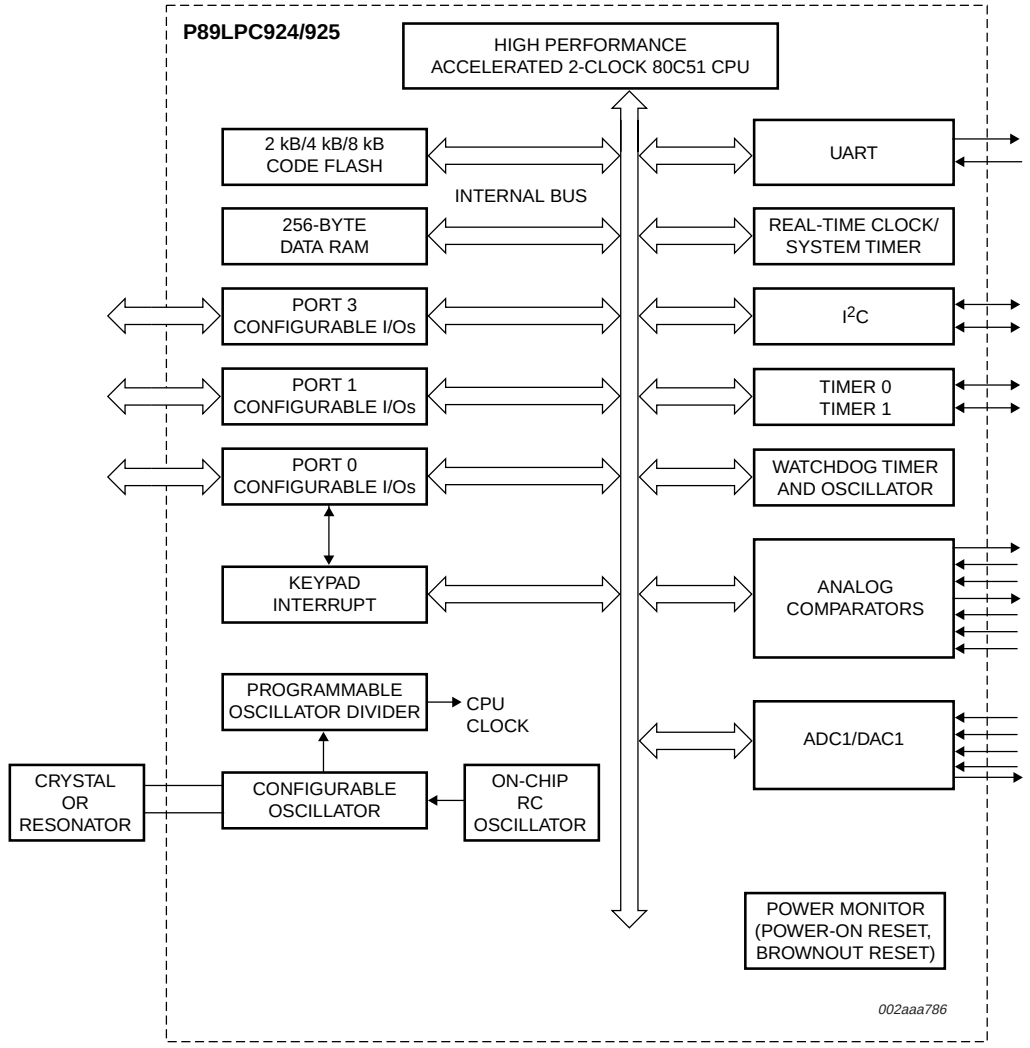

Fig 1. Block diagram.

7. Special function registers

Remark: Special Function Registers (SFRs) accesses are restricted in the following ways:

- User must **not** attempt to access any SFR locations not defined.
- Accesses to any defined SFR locations must be strictly for the functions for the SFRs.
- SFR bits labeled '-', '0' or '1' can **only** be written and read as follows:
  - '-' Unless otherwise specified, **must** be written with '0', but can return any value when read (even if it was written with '0'). It is a reserved bit and may be used in future derivatives.
  - '0' **must** be written with '0', and will return a '0' when read.
  - '1' **must** be written with '1', and will return a '1' when read.

Table 4: Special function registers

** indicates SFRs that are bit addressable.*

Name	Description	SFR addr.	Bit functions and addresses								Reset value	
			MSB							LSB	Hex	Binary
	Bit address		E7	E6	E5	E4	E3	E2	E1	E0		
ACC*	Accumulator	E0H									00	00000000
ADCON1	A/D control register 1	97H	ENBI1	ENADCI 1	TMM1	EDGE1	ADCI1	ENADC1	ADCS11	ADCS10	00	00000000
ADINS	A/D input select	A3H	ADI13	ADI12	ADI11	ADI10	-	-	-	-	00	00000000
ADMODA	A/D mode register A	C0H	BNDI1	BURST1	SCC1	SCAN1	-	-	-	-	00	00000000
ADMODB	A/D mode register B	A1H	CLK2	CLK1	CLK0	-	ENDAC1	-	BSA1	-	00	000x0000
AD1BH	A/D_1 boundary high register	C4H									FF	11111111
AD1BL	A/D_1 boundary low register	BCH									00	00000000
AD1DAT0	A/D_1 data register 0	D5H									00	00000000
AD1DAT1	A/D_1 data register 1	D6H									00	00000000
AD1DAT2	A/D_1 data register 2	D7H									00	00000000
AD1DAT3	A/D_1 data register 3	F5H									00	00000000
AUXR1	Auxiliary function register	A2H	CLKLP	EBRR	ENT1	ENT0	SRST	0	-	DPS	00[1]	000000x0
	Bit address		F7	F6	F5	F4	F3	F2	F1	F0		
B*	B register	F0H									00	00000000
BRGR0[2]	Baud rate generator rate LOW	BEH									00	00000000
BRGR1[2]	Baud rate generator rate HIGH	BFH									00	00000000
BRGCON	Baud rate generator control	BDH	-	-	-	-	-	-	SBRGS	BRGEN	00	xxxxxx00
CMP1	Comparator 1 control register	ACH	-	-	CE1	CP1	CN1	OE1	CO1	CMF1	00[1]	xx000000
CMP2	Comparator 2 control register	ADH	-	-	CE2	CP2	CN2	OE2	CO2	CMF2	00[1]	xx000000
DIVM	CPU clock divide-by-M control	95H									00	00000000
DPTR	Data pointer (2 bytes)											
DPH	Data pointer HIGH	83H									00	00000000
DPL	Data pointer LOW	82H									00	00000000
FMADRH	Program Flash address HIGH	E7H									00	00000000
FMADRL	Program Flash address LOW	E6H									00	00000000

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Table 4: Special function registers…*continued*

** indicates SFRs that are bit addressable.*

Name	Description	SFR addr.	Bit functions and addresses								Reset value	
			MSB							LSB	Hex	Binary
FMCON	Program Flash control (Read)	E4H	BUSY	-	-	-	HVA	HVE	SV	OI	70	01110000
	Program Flash control (Write)	E4H	FMCMD.7	FMCMD.6	FMCMD.5	FMCMD.4	FMCMD.3	FMCMD.2	FMCMD.1	FMCMD.0		
FMDATA	Program Flash data	E5H									00	00000000
I2ADR	I^2C slave address register	DBH	I2ADR.6	I2ADR.5	I2ADR.4	I2ADR.3	I2ADR.2	I2ADR.1	I2ADR.0	GC	00	00000000
	Bit address		**DF**	**DE**	**DD**	**DC**	**DB**	**DA**	**D9**	**D8**		
I2CON*	I^2C control register	D8H	-	I2EN	STA	STO	SI	AA	-	CRSEL	00	x00000x0
I2DAT	I^2C data register	DAH										
I2SCLH	Serial clock generator/SCL duty cycle register HIGH	DDH									00	00000000
I2SCLL	Serial clock generator/SCL duty cycle register LOW	DCH									00	00000000
I2STAT	I^2C status register	D9H	STA.4	STA.3	STA.2	STA.1	STA.0	0	0	0	F8	11111000
	Bit address		**AF**	**AE**	**AD**	**AC**	**AB**	**AA**	**A9**	**A8**		
IEN0*	Interrupt enable 0	A8H	EA	EWDRT	EBO	ES/ESR	ET1	EX1	ET0	EX0	00[1]	00000000
	Bit address		**EF**	**EE**	**ED**	**EC**	**EB**	**EA**	**E9**	**E8**		
IEN1*	Interrupt enable 1	E8H	EAD	EST	-	-	-	EC	EKBI	EI2C	00[1]	00x00000
	Bit address		**BF**	**BE**	**BD**	**BC**	**BB**	**BA**	**B9**	**B8**		
IP0*	Interrupt priority 0	B8H	-	PWDRT	PBO	PS/PSR	PT1	PX1	PT0	PX0	00[1]	x0000000
IP0H	Interrupt priority 0 HIGH	B7H	-	PWDRTH	PBOH	PSH/PSRH	PT1H	PX1H	PT0H	PX0H	00[1]	x0000000
	Bit address		**FF**	**FE**	**FD**	**FC**	**FB**	**FA**	**F9**	**F8**		
IP1*	Interrupt priority 1	F8H	PAD	PST	-	-	-	PC	PKBI	PI2C	00[1]	00x00000
IP1H	Interrupt priority 1 HIGH	F7H	PADH	PSTH	-	-	-	PCH	PKBIH	PI2CH	00[1]	00x00000
KBCON	Keypad control register	94H	-	-	-	-	-	-	PATN_SEL	KBIF	00[1]	xxxxxx00
KBMASK	Keypad interrupt mask register	86H									00	00000000
KBPATN	Keypad pattern register	93H									FF	11111111
	Bit address		**87**	**86**	**85**	**84**	**83**	**82**	**81**	**80**		

8. Functional description

Remark: Please refer to the *P89LPC924/925 User's Manual* for a more detailed functional description.

8.1 Enhanced CPU

The P89LPC924/925 uses an enhanced 80C51 CPU which runs at 6 times the speed of standard 80C51 devices. A machine cycle consists of two CPU clock cycles, and most instructions execute in one or two machine cycles.

8.2 Clocks

8.2.1 Clock definitions

The P89LPC924/925 device has several internal clocks as defined below:

OSCCLK — Input to the DIVM clock divider. OSCCLK is selected from one of four clock sources (see Figure 4) and can also be optionally divided to a slower frequency (see Section 8.7 "CPU Clock (CCLK) modification: DIVM register").

Note: f_{osc} is defined as the OSCCLK frequency.

CCLK — CPU clock; output of the clock divider. There are two CCLK cycles per machine cycle, and most instructions are executed in one to two machine cycles (two or four CCLK cycles).

RCCLK — The internal 7.373 MHz RC oscillator output.

PCLK — Clock for the various peripheral devices and is CCLK/2

8.2.2 CPU clock (OSCCLK)

The P89LPC924/925 provides several user-selectable oscillator options in generating the CPU clock. This allows optimization for a range of needs from high precision to lowest possible cost. These options are configured when the FLASH is programmed and include an on-chip watchdog oscillator, an on-chip RC oscillator, an oscillator using an external crystal, or an external clock source. The crystal oscillator can be optimized for low, medium, or high frequency crystals covering a range from 20 kHz to 12 MHz.

8.2.3 Low speed oscillator option

This option supports an external crystal in the range of 20 kHz to 100 kHz. Ceramic resonators are also supported in this configuration.

8.2.4 Medium speed oscillator option

This option supports an external crystal in the range of 100 kHz to 4 MHz. Ceramic resonators are also supported in this configuration.

8.2.5 High speed oscillator option

This option supports an external crystal in the range of 4 MHz to 18 MHz. Ceramic resonators are also supported in this configuration. **When using an oscillator frequency above 12 MHz, the reset input function of P1.5 must be enabled. An external circuit is required to hold the device in reset at power-up until V_{DD} has reached its specified level. When system power is removed V_{DD} will fall below**

8.9.2 Features

- 8-bit, 4-channel multiplexed input, successive approximation A/D converter.
- Four result registers.
- Six operating modes
  - Fixed channel, single conversion mode
  - Fixed channel, continuous conversion mode
  - Auto scan, single conversion mode
  - Auto scan, continuous conversion mode
  - Dual channel, continuous conversion mode
  - Single step mode
- Three conversion start modes
  - Timer triggered start
  - Start immediately
  - Edge triggered
- 8-bit conversion time of ≥ 3.9 μs at an ADC clock of 3.3 MHz
- Interrupt or polled operation
- Boundary limits interrupt
- DAC output to a port pin with high output impedance
- Clock divider
- Power down mode

8.9.3 A/D operating modes

Fixed channel, single conversion mode: A single input channel can be selected for conversion. A single conversion will be performed and the result placed in the result register which corresponds to the selected input channel. An interrupt, if enabled, will be generated after the conversion completes.

Fixed channel, continuous conversion mode: A single input channel can be selected for continuous conversion. The results of the conversions will be sequentially placed in the four result registers. An interrupt, if enabled, will be generated after every four conversions. Additional conversion results will again cycle through the four result registers, overwriting the previous results. Continuous conversions continue until terminated by the user.

Auto scan, single conversion mode: Any combination of the four input channels can be selected for conversion. A single conversion of each selected input will be performed and the result placed in the result register which corresponds to the selected input channel. An interrupt, if enabled, will be generated after all selected channels have been converted. If only a single channel is selected this is equivalent to single channel, single conversion mode.

Auto scan, continuous conversion mode: Any combination of the four input channels can be selected for conversion. A conversion of each selected input will be performed and the result placed in the result register which corresponds to the selected input channel. An interrupt, if enabled, will be generated after all selected

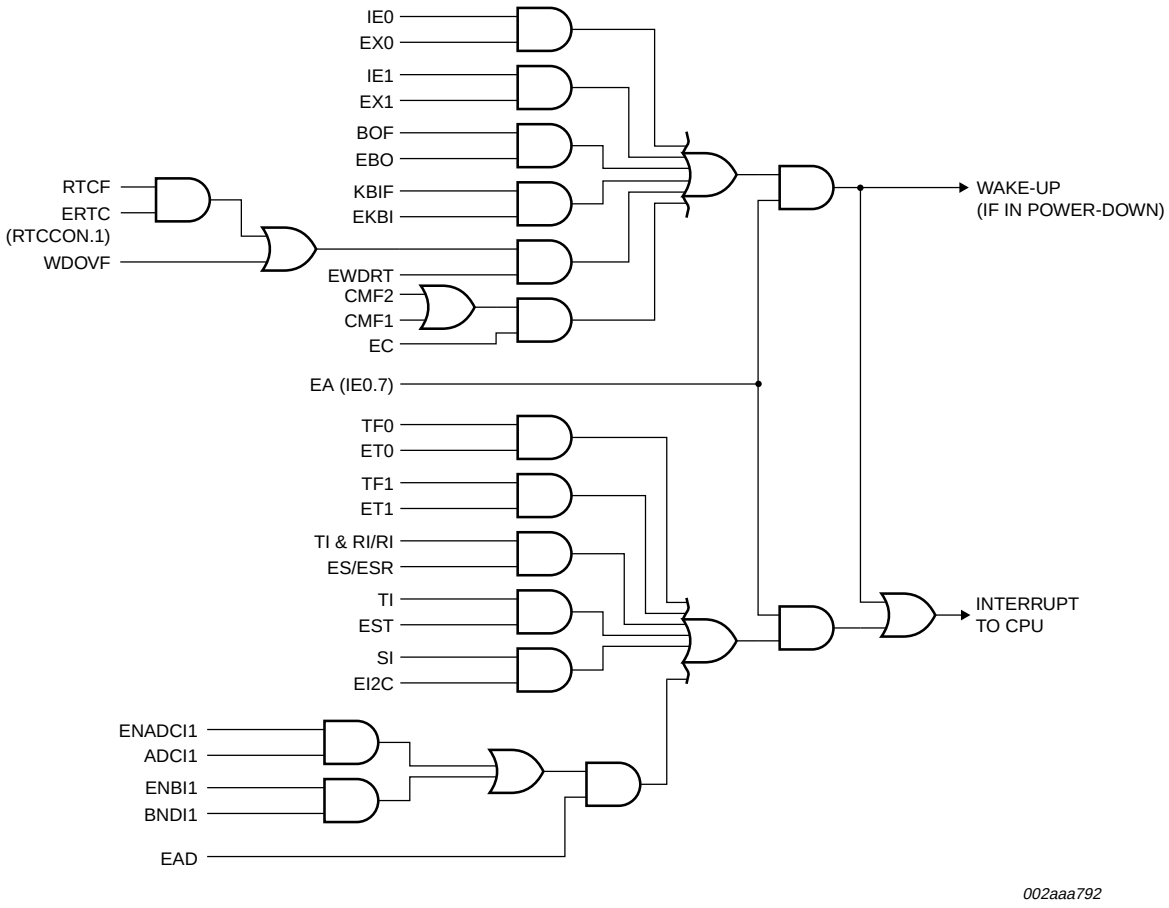


Fig 6. Interrupt sources, interrupt enables, and power-down wake-up sources.

8.13 I/O ports

The P89LPC924/925 has three I/O ports: Port 0, Port 1, and Port 3. Ports 0 and 1 are 8-bit ports, and Port 3 is a 2-bit port. The exact number of I/O pins available depend upon the clock and reset options chosen, as shown in Table 6.

Table 6: Number of I/O pins available

Clock source	Reset option	Number of I/O pins (20-pin package)
On-chip oscillator or watchdog oscillator	No external reset (except during power-up)	18
	External $\overline{\text{RST}}$ pin supported[1]	17
External clock input	No external reset (except during power-up)	17
	External $\overline{\text{RST}}$ pin supported[1]	16
Low/medium/high speed oscillator (external crystal or resonator)	No external reset (except during power-up)	16
	External $\overline{\text{RST}}$ pin supported[1]	15

[1] Required for operation above 12 MHz.

8.15 Power reduction modes

The P89LPC924/925 supports three different power reduction modes. These modes are Idle mode, Power-down mode, and total Power-down mode.

8.15.1 Idle mode

Idle mode leaves peripherals running in order to allow them to activate the processor when an interrupt is generated. Any enabled interrupt source or reset may terminate Idle mode.

8.15.2 Power-down mode

The Power-down mode stops the oscillator in order to minimize power consumption. The P89LPC924/925 exits Power-down mode via any reset, or certain interrupts. In Power-down mode, the power supply voltage may be reduced to the RAM keep-alive voltage V_{RAM}. This retains the RAM contents at the point where Power-down mode was entered. SFR contents are not guaranteed after V_{DD} has been lowered to V_{RAM}, therefore it is highly recommended to wake up the processor via reset in this case. V_{DD} must be raised to within the operating range before the Power-down mode is exited.

Some chip functions continue to operate and draw power during Power-down mode, increasing the total power used during Power-down. These include: Brownout detect, Watchdog Timer, Comparators (note that Comparators can be powered-down separately), and Real-Time Clock (RTC)/System Timer. The internal RC oscillator is disabled unless both the RC oscillator has been selected as the system clock AND the RTC is enabled.

8.15.3 Total Power-down mode

This is the same as Power-down mode except that the brownout detection circuitry and the voltage comparators are also disabled to conserve additional power. The internal RC oscillator is disabled unless both the RC oscillator has been selected as the system clock **and** the RTC is enabled. If the internal RC oscillator is used to clock the RTC during Power-down, there will be high power consumption. Please use an external low frequency clock to achieve low power with the Real-Time Clock running during Power-down.

8.16 Reset

The P1.5/$\overline{\text{RST}}$ pin can function as either an active-LOW reset input or as a digital input, P1.5. The RPE (Reset Pin Enable) bit in UCFG1, when set to ‘1’, enables the external reset input function on P1.5. When cleared, P1.5 may be used as an input pin.

Remark: During a power-up sequence, the RPE selection is overridden and this pin will always function as a reset input. **An external circuit connected to this pin should not hold this pin LOW during a power-on sequence as this will keep the device in reset.** After power-up this input will function either as an external reset input or as a digital input as defined by the RPE bit. Only a power-up reset will temporarily override the selection defined by RPE bit. Other sources of reset will not override the RPE bit.

Remark: During a power cycle, V_{DD} must fall below V_{POR} (see Table 8 “DC electrical characteristics” on page 40) before power is reapplied, in order to ensure a power-on reset.

Reset can be triggered from the following sources:

- External reset pin (during power-up or if user configured via UCFG1. This option must be used for an oscillator frequency above 12 MHz);
- Power-on detect;
- Brownout detect;
- Watchdog Timer;
- Software reset;
- UART break character detect reset.

For every reset source, there is a flag in the Reset Register, RSTSRC. The user can read this register to determine the most recent reset source. These flag bits can be cleared in software by writing a ‘0’ to the corresponding bit. More than one flag bit may be set:

- During a power-on reset, both POF and BOF are set but the other flag bits are cleared.
- For any other reset, previously set flag bits that have not been cleared will remain set.

8.16.1 Reset vector

Following reset, the P89LPC924/925 will fetch instructions from either address 0000h or the Boot address. The Boot address is formed by using the Boot Vector as the high byte of the address and the low byte of the address = 00h.

The Boot address will be used if a UART break reset occurs, or the non-volatile Boot Status bit (BOOTSTAT.0) = 1, or the device is forced into ISP mode during power-on (see *P89LPC924/925 User’s Manual*). Otherwise, instructions will be fetched from address 0000H.

8.17 Timers/counters 0 and 1

The P89LPC924/925 has two general purpose counter/timers which are upward compatible with the standard 80C51 Timer 0 and Timer 1. Both can be configured to operate either as timers or event counter. An option to automatically toggle the T0 and/or T1 pins upon timer overflow has been added.

In the ‘Timer’ function, the register is incremented every machine cycle.

In the ‘Counter’ function, the register is incremented in response to a 1-to-0 transition at its corresponding external input pin, T0 or T1. In this function, the external input is sampled once during every machine cycle.

Timer 0 and Timer 1 have five operating modes (modes 0, 1, 2, 3 and 6). Modes 0, 1, 2 and 6 are the same for both Timers/Counters. Mode 3 is different.

8.19.6 Framing error

Framing error is reported in the status register (SSTAT). In addition, if SMOD0 (PCON.6) is '1', framing errors can be made available in SCON.7 respectively. If SMOD0 is '0', SCON.7 is SM0. It is recommended that SM0 and SM1 (SCON.7:6) are set up when SMOD0 is '0'.

8.19.7 Break detect

Break detect is reported in the status register (SSTAT). A break is detected when 11 consecutive bits are sensed LOW. The break detect can be used to reset the device and force the device into ISP mode.

8.19.8 Double buffering

The UART has a transmit double buffer that allows buffering of the next character to be written to SBUF while the first character is being transmitted. Double buffering allows transmission of a string of characters with only one stop bit between any two characters, as long as the next character is written between the start bit and the stop bit of the previous character.

Double buffering can be disabled. If disabled (DBMOD, i.e., SSTAT.7 = '0'), the UART is compatible with the conventional 80C51 UART. If enabled, the UART allows writing to SnBUF while the previous data is being shifted out. Double buffering is only allowed in Modes 1, 2 and 3. When operated in Mode 0, double buffering must be disabled (DBMOD = '0').

8.19.9 Transmit interrupts with double buffering enabled (Modes 1, 2 and 3)

Unlike the conventional UART, in double buffering mode, the Tx interrupt is generated when the double buffer is ready to receive new data.

8.19.10 The 9th bit (bit 8) in double buffering (Modes 1, 2 and 3)

If double buffering is disabled TB8 can be written before or after SBUF is written, as long as TB8 is updated some time before that bit is shifted out. TB8 must not be changed until the bit is shifted out, as indicated by the Tx interrupt.

If double buffering is enabled, TB8 **must** be updated before SBUF is written, as TB8 will be double-buffered together with SBUF data.

8.20 I²C-bus serial interface

I²C-bus uses two wires (SDA and SCL) to transfer information between devices connected to the bus, and it has the following features:

- Bidirectional data transfer between masters and slaves
- Multimaster bus (no central master)
- Arbitration between simultaneously transmitting masters without corruption of serial data on the bus
- Serial clock synchronization allows devices with different bit rates to communicate via one serial bus
- Serial clock synchronization can be used as a handshake mechanism to suspend and resume serial transfer
- The I²C-bus may be used for test and diagnostic purposes.

A typical I²C-bus configuration is shown in Figure 8. The P89LPC924/925 device provides a byte-oriented I²C-bus interface that supports data transfers up to 400 kHz.

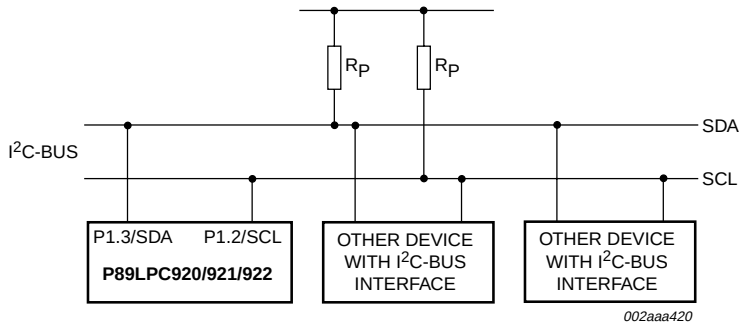


Fig 8. I²C-bus configuration.

8.21.2 Comparator interrupt

Each comparator has an interrupt flag contained in its configuration register. This flag is set whenever the comparator output changes state. The flag may be polled by software or may be used to generate an interrupt. The two comparators use one common interrupt vector. If both comparators enable interrupts, after entering the interrupt service routine, the user needs to read the flags to determine which comparator caused the interrupt.

8.21.3 Comparators and power reduction modes

Either or both comparators may remain enabled when Power-down or Idle mode is activated, but both comparators are disabled automatically in Total Power-down mode. If a comparator interrupt is enabled (except in Total Power-down mode), a change of the comparator output state will generate an interrupt and wake up the processor. If the comparator output to a pin is enabled, the pin should be configured in the push-pull mode in order to obtain fast switching times while in Power-down mode. The reason is that with the oscillator stopped, the temporary strong pull-up that normally occurs during switching on a quasi-bidirectional port pin does not take place.

Comparators consume power in Power-down and Idle modes, as well as in the normal operating mode. This fact should be taken into account when system power consumption is an issue. To minimize power consumption, the user can disable the comparators via PCONA.5, or put the device in Total Power-down mode.

8.22 Keypad interrupt (KBI)

The Keypad Interrupt function is intended primarily to allow a single interrupt to be generated when Port 0 is equal to or not equal to a certain pattern. This function can be used for bus address recognition or keypad recognition. The user can configure the port via SFRs for different tasks.

The Keypad Interrupt Mask Register (KBMASK) is used to define which input pins connected to Port 0 can trigger the interrupt. The Keypad Pattern Register (KBPATN) is used to define a pattern that is compared to the value of Port 0. The Keypad Interrupt Flag (KBIF) in the Keypad Interrupt Control Register (KBCON) is set when the condition is matched while the Keypad Interrupt function is active. An interrupt will be generated if enabled. The PATN_SEL bit in the Keypad Interrupt Control Register (KBCON) is used to define equal or not-equal for the comparison.

In order to use the Keypad Interrupt as an original KBI function like in 87LPC76x series, the user needs to set KBPATN = 0FFH and PATN_SEL = 1 (not equal), then any key connected to Port 0 which is enabled by the KBMASK register will cause the hardware to set KBIF and generate an interrupt if it has been enabled. The interrupt may be used to wake up the CPU from Idle or Power-down modes. This feature is particularly useful in handheld, battery-powered systems that need to carefully manage power consumption yet also need to be convenient to use.

In order to set the flag and cause an interrupt, the pattern on Port 0 must be held longer than 6 CCLKs.

8.25 Flash program memory

8.25.1 General description

The P89LPC924/925 Flash memory provides in-circuit electrical erasure and programming. The Flash can be read, erased, or written as bytes. The Sector and Page Erase functions can erase any Flash sector (1 kB) or page (64 bytes). The Chip Erase operation will erase the entire program memory. In-System Programming and standard parallel programming are both available. On-chip erase and write timing generation contribute to a user-friendly programming interface. The P89LPC924/925 Flash reliably stores memory contents even after 100,000 erase and program cycles. The cell is designed to optimize the erase and programming mechanisms. The P89LPC924/925 uses V_{DD} as the supply voltage to perform the Program/Erase algorithms.

8.25.2 Features

- Parallel programming with industry-standard commercial programmers.
- In-Circuit serial Programming (ICP) with industry-standard commercial programmers.
- IAP-Lite allows individual and multiple bytes of code memory to be used for data storage and programmed under control of the end application.
- Internal fixed boot ROM, containing low-level In-Application Programming (IAP) routines that can be called from the end application (in addition to IAP-Lite).
- Default serial loader providing In-System Programming (ISP) via the serial port, located in upper end of user program memory.
- Boot vector allows user-provided Flash loader code to reside anywhere in the Flash memory space, providing flexibility to the user.
- Programming and erase over the full operating voltage range.
- Read/Programming/Erase using ISP/IAP/IAP-Lite.
- Any flash program operation in 2 ms.
- Any flash erase operation in 4 ms.
- Programmable security for the code in the Flash for each sector.
- >100,000 typical erase/program cycles for each byte.
- 10 year minimum data retention.

8.25.3 ISP and IAP capabilities of the P89LPC924/925

Flash organization: The P89LPC924/925 program memory consists of four/eight 1 kB sectors. Each sector can be further divided into 64-byte pages. In addition to sector erase, page erase, and byte erase, a 64-byte page register is included which allows from 1 to 64 bytes of a given page to be programmed at the same time, substantially reducing overall programming time. An In-Application Programming (IAP) interface is provided to allow the end user's application to erase and reprogram the user code memory. In addition, erasing and reprogramming of user-programmable bytes including UCFG1, the Boot Status Byte and the Boot Vector are supported. As shipped from the factory, the upper 512 bytes of user code space contains a serial In-System Programming (ISP) routine allowing for the device to be programmed in circuit through the serial port.

9. Limiting values

Table 7: Limiting values[1]

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$T_{amb(bias)}$	operating bias ambient temperature		–55	+125	°C
T_{stg}	storage temperature range		–65	+150	°C
V_{xtal}	voltage on XTAL1, XTAL2 pin to V_{SS}		-	V_{DD} + 0.5	V
V_n	voltage on any other pin to V_{SS}		–0.5	+5.5	V
$I_{OH(I/O)}$	HIGH-level output current per I/O pin		-	8	mA
$I_{OL(I/O)}$	LOW-level output current per I/O pin		-	20	mA
$I_{I/O(tot)(max)}$	maximum total I/O current		-	80	mA
$P_{tot(pack)}$	total power dissipation per package	based on package heat transfer, not device power consumption	-	1.5	W

[1] The following applies to Limiting values:

a) Stresses above those listed under Table 7 may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any conditions other than those described in Table 8 “DC electrical characteristics”, Table 9 “AC characteristics” and Table 10 “AC characteristics” of this specification are not implied.

b) This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maximum.

c) Parameters are valid over operating temperature range unless otherwise specified. All voltages are with respect to V_{SS} unless otherwise noted.

10. Static characteristics

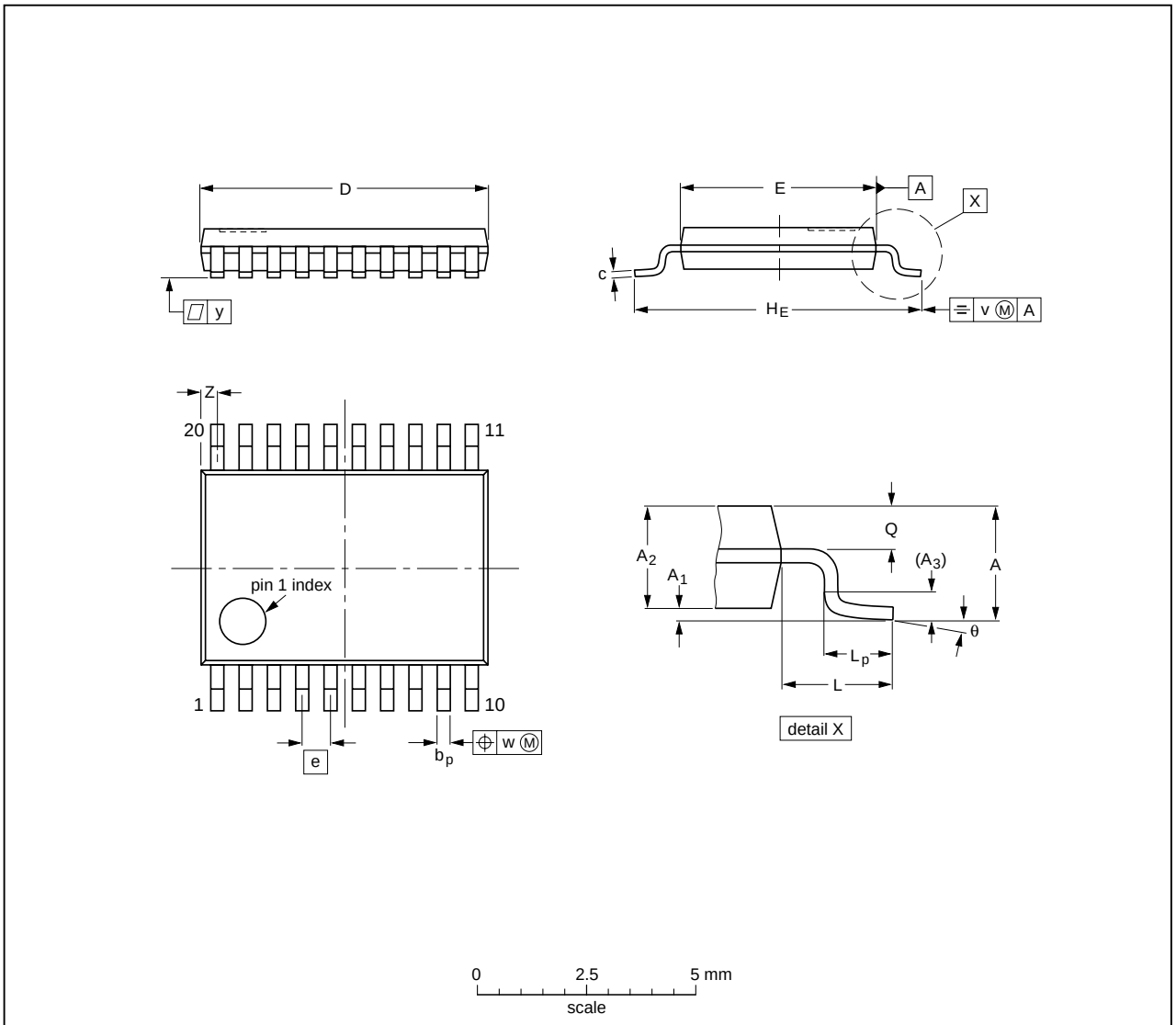
Table 8: DC electrical characteristics

V_{DD} = 2.4 V to 3.6 V, unless otherwise specified.
T_{amb} = −40 °C to +85 °C for industrial, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
$I_{DD(oper)}$	power supply current, operating	3.6 V; 12 MHz	[2]	-	9	15	mA
		3.6 V; 18 MHz	[2]	-	14	23	mA
$I_{DD(idle)}$	power supply current, Idle mode	3.6 V; 12 MHz	[2]	-	3.25	5	mA
		3.6 V; 18 MHz	[2]	-	5	7	mA
$I_{DD(PD)}$	power supply current, Power-down mode, voltage comparators powered-down	3.6 V	[2]	-	55	80	µA
$I_{DD(TPD)}$	power supply current, Total Power-down mode	3.6 V	[2]	-	1	5	µA
$(dV_{DD}/dt)_r$	V_{DD} rise rate			-	-	2	mV/µs
$(dV_{DD}/dt)_f$	V_{DD} fall rate			-	-	50	mV/µs
V_{POR}	Power-on reset detect voltage			-	-	0.2	V
V_{RAM}	RAM keep-alive voltage			1.5	-	-	V
$V_{th(HL)}$	negative-going threshold voltage	except SCL, SDA		$0.22V_{DD}$	$0.4V_{DD}$	-	V
V_{IL}	LOW-level input voltage	SCL, SDA only		–0.5	-	$0.3V_{DD}$	V
$V_{th(LH)}$	positive-going threshold voltage	except SCL, SDA		-	$0.6V_{DD}$	$0.7V_{DD}$	V
V_{IH}	HIGH-level input voltage	SCL, SDA only		$0.7V_{DD}$	-	5.5	V
V_{hys}	hysteresis voltage	Port 1		-	$0.2V_{DD}$	-	V
V_{OL}	LOW-level output voltage; all ports, all modes except Hi-Z	I_{OL} = 20 mA	[3]	-	0.6	1.0	V
		I_{OL} = 3.2 mA	[3]	-	0.2	0.3	V
V_{OH}	HIGH-level output voltage, all ports	I_{OH} = –3.2 mA; push-pull mode		V_{DD} – 0.7	V_{DD} – 0.4	-	V
		I_{OH} = –20 µA; quasi-bidirectional mode		V_{DD} – 0.3	V_{DD} – 0.2	-	V
C_{ig}	input/output pin capacitance		[4]	-	-	15	pF
I_{IL}	logical 0 input current, all ports	V_{IN} = 0.4 V	[5]	-	-	–80	µA
I_{LI}	input leakage current, all ports	V_{IN} = V_{IL} or V_{IH}	[6]	-	-	± 10	µA
I_{TL}	logical 1-to-0 transition current, all ports	V_{IN} = 2.0 V at V_{DD} = 3.6 V	[7], [8]	–30	-	–450	µA
R_{RST}	internal reset pull-up resistor			10	-	30	kΩ

14. Package outline

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm **SOT360-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8^o 0^o

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT360-1		MO-153				~~99-12-27~~ 03-02-19

Fig 15. TSSOP20 (SOT360-1).

15. Revision history

Table 14: Revision history

Rev	Date	CPCN	Description
03	20041215	-	**Product data (9397 750 14471)** Modification: • Added 18 MHz information.
02	20040615	-	**Product data (9397 750 13459)**
01	20040309	-	**Objective data (9397 750 12879)**

16. Data sheet status

Level	Data sheet status[1]	Product status[2][3]	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

[1] Please consult the most recently issued data sheet before initiating or completing a design.

[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

17. Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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